

# PH3n High Performance Heat Spreader



## Features

- Gives a typical junction temperature reduction of 20°C
- Gives design flexibility
- Die cut for custom shapes

## Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

## Properties

- REACH Compliant
- RoHS Compliant

Property	PH3n			Test Method	Unit
Colour	Black	Black	Black	Visual	-
Thickness	0.062	0.07	0.1	-	mm
Metal layer	CU foil	CU foil	CU foil	-	-
PET layer thickness	0.025	0.025	0.025	ADTM D374	mm
Coating layer thickness	0.025	0.025	0.025	-	mm
Metal layer thickness	0.012	0.02	0.02	-	mm
Filler	Nano tube	Nano tube	Nano tube	-	-
Application temperature	-30 to 120	-30 to 120	-30 to 120	-	°C
Short time temp. @ 30sec	200	200	200	-	°C
Low molecular weight Siloxane content	0	0	0	-	ppm
Heat emissivity coefficient	0.96	0.96	0.96	ADTM D149	1
Dielectric strength (AV)	>2	>2	>2	ADTM D149	kV
Metal layer thermal conductivity	400	400	400	ADTM D5470	W/mk
Coated layer thermal conductivity	1.2	1.2	1.2	ADTM D5470	W/mk

Available with an adhesive backing

